

A 167-processor 65 nm Computational Platform with Per-Processor Dynamic Supply Voltage and Dynamic Clock Frequency Scaling

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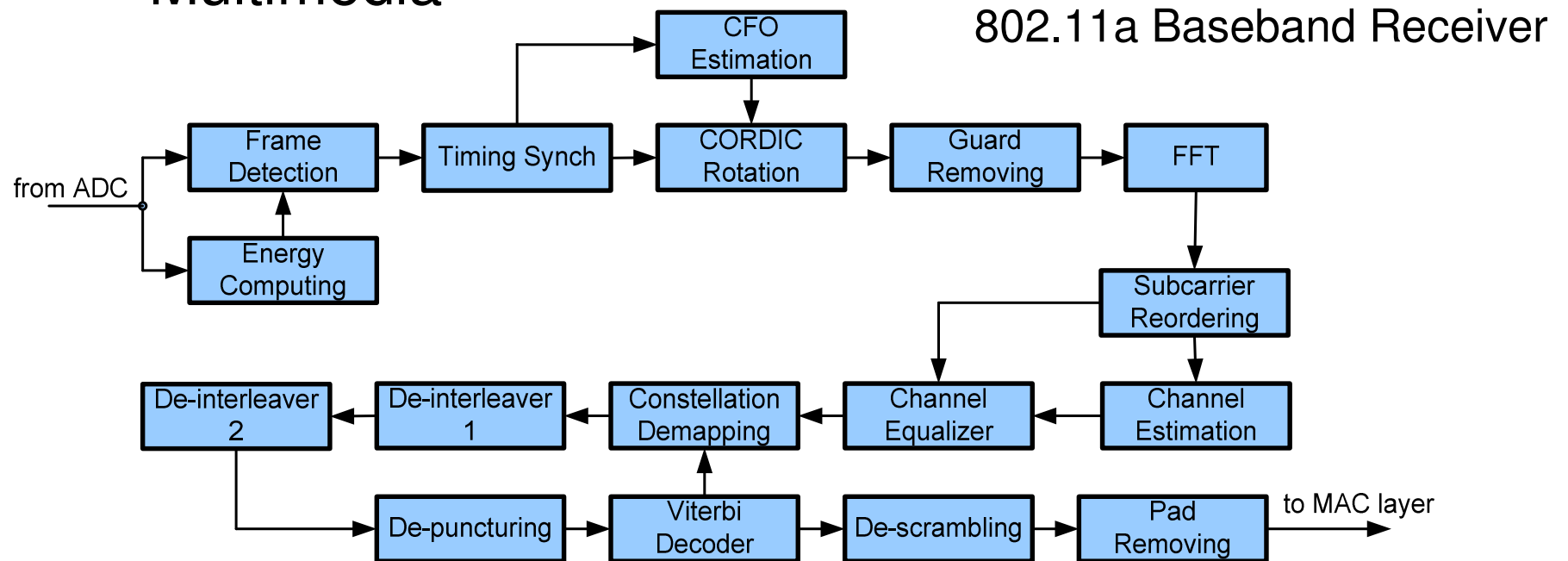
***VLSI Computation Lab
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Outline

- **Background and the First Generation AsAP**
- The Second Generation AsAP
 - Processors and Shared Memories
 - On-chip Communication
 - DVFS
- Analysis and Summary

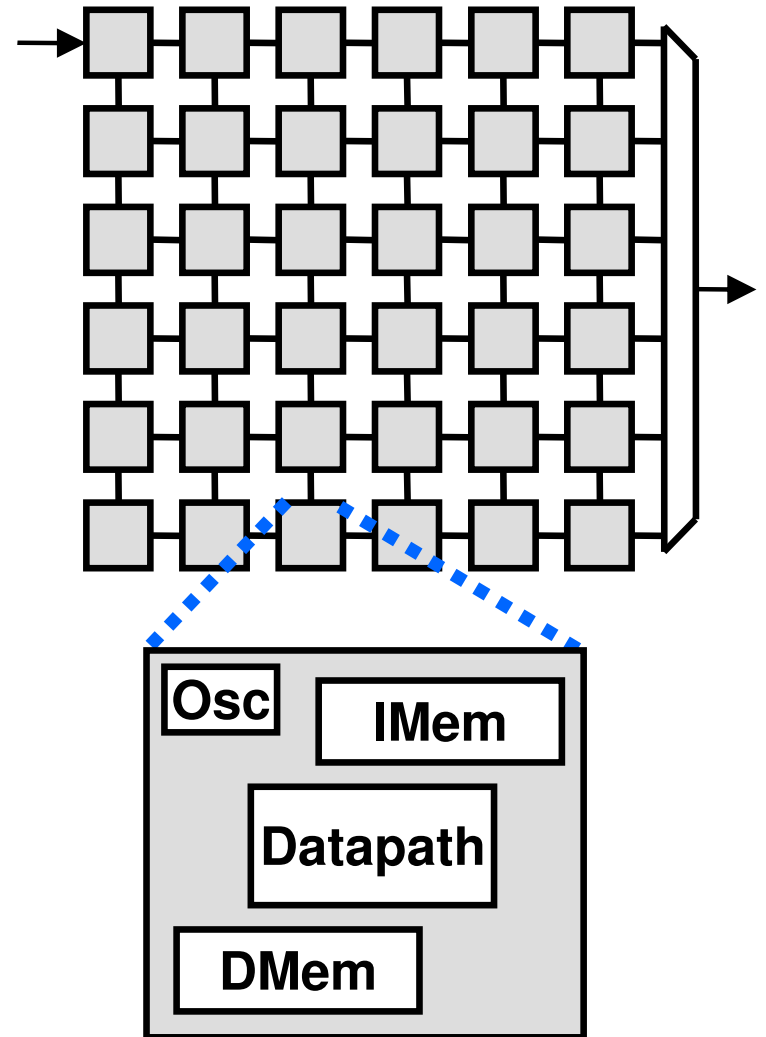
Project Motivation

- Fully programmable and reconfig. architecture
- High energy efficiency and performance
- Exploit task-level parallelism in:
 - Digital Signal Processing
 - Multimedia



Asynchronous Array of Simple Processors (AsAP)

- Key Ideas:
 - Programmable, small, and simple fine-grained cores
 - Small local memories sufficient for DSP kernels
 - Globally Asynchronous and Locally Synchronous (GALS) clocking
 - Independent clock frequencies on every core
 - Local oscillator halts when processor is idle



Asynchronous Array of Simple Processors (AsAP)

- Key Ideas, con't:
 - 2D mesh, circuit-switched network architecture
 - Nearest-neighbor communication only
 - Low area overhead
 - Easily scalable array
 - Increased tolerance to process variations
- 36-processor fully-functional chip, 0.18 μm , 610 MHz @ 2.0 V, 0.66 mm^2 per processor, 802.11a/g tx consumes 407 mW @ 300 MHz
[ISSCC 06, HotChips 06, IEEE Micro 07, TVLSI 07, JSSC 08,...]

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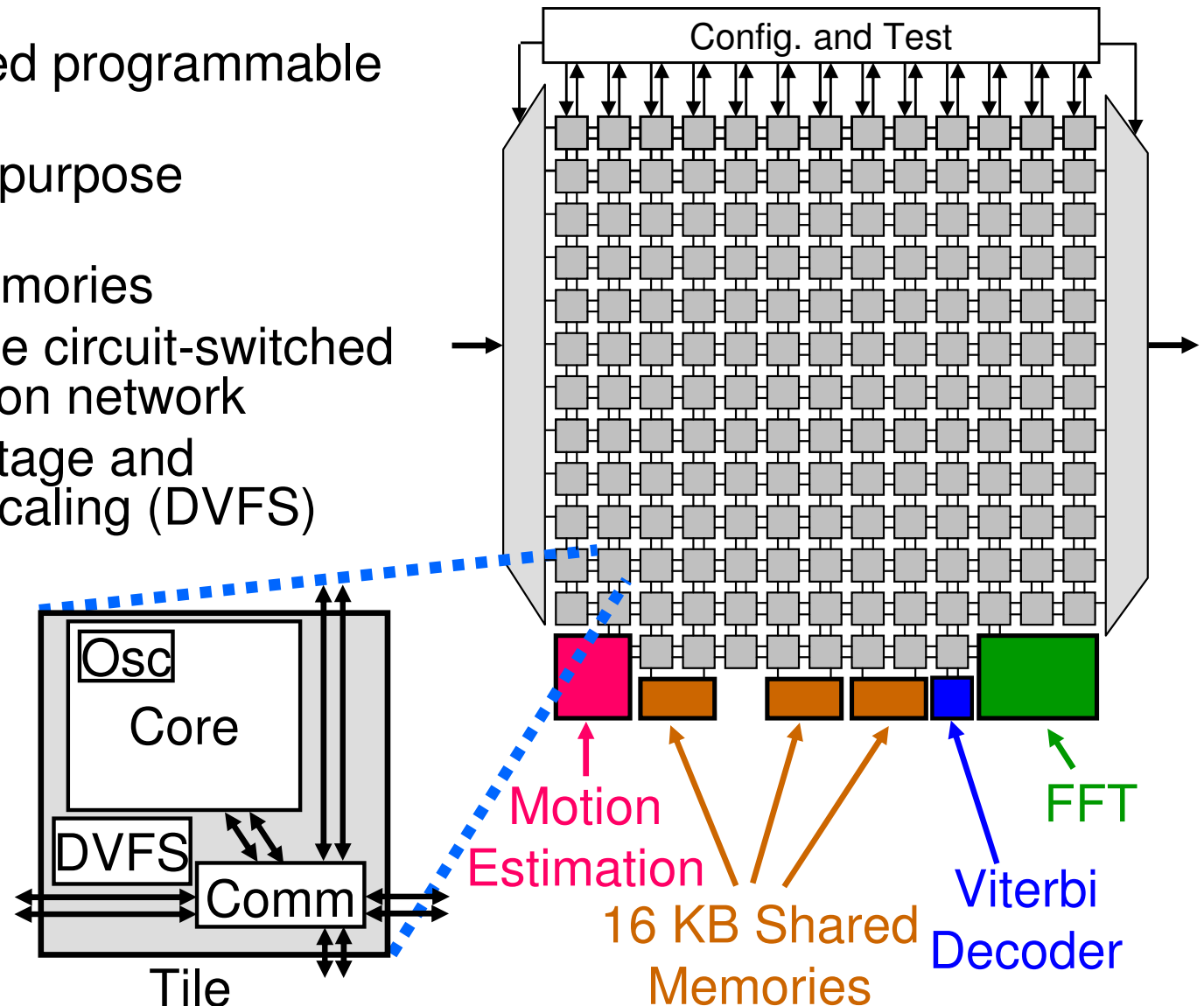
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New Challenges Addressed

- Reduction in the power dissipation of
 - Lightly-loaded processors (lowering V_{dd})
 - Unused processors (leakage)
- Achieving very high efficiencies and speed on common demanding tasks such as FFTs, video motion estimation, and Viterbi decoding
- Larger, area efficient on-chip memories
- Efficient, low overhead communication between distant processors

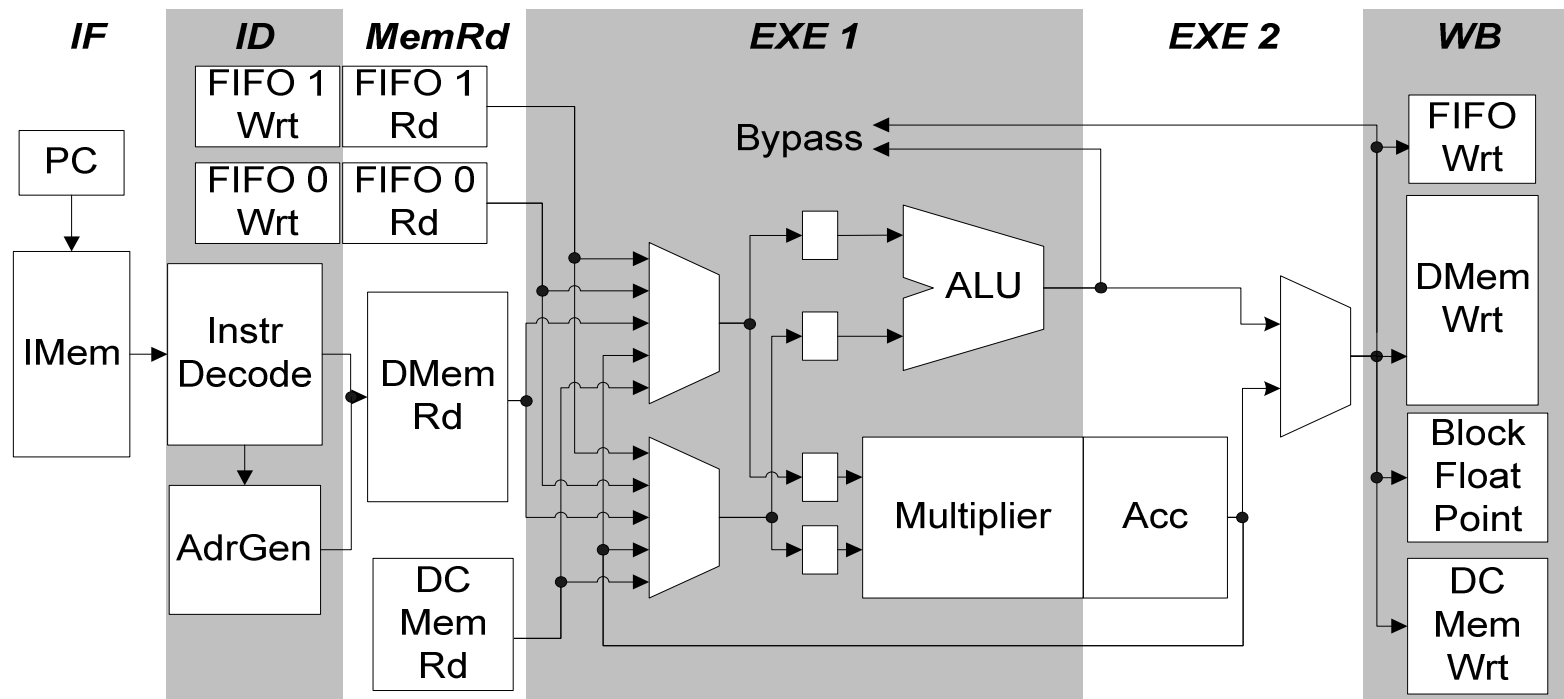
167-processor Computational Platform

- Key features
 - 164 Enhanced programmable processors
 - 3 Dedicated-purpose processors
 - 3 Shared memories
 - Long-distance circuit-switched communication network
 - Dynamic Voltage and Frequency Scaling (DVFS)



Homogenous Processors

- 164 in-order, single-issue, 6-stage processors
 - 16-bit datapath with RISC-like instructions
 - 128x16-bit data memory (DMEM)
 - 128x35-bit instruction memory (IMEM)
 - Two 64x16-bit FIFOs for inter-processor communication

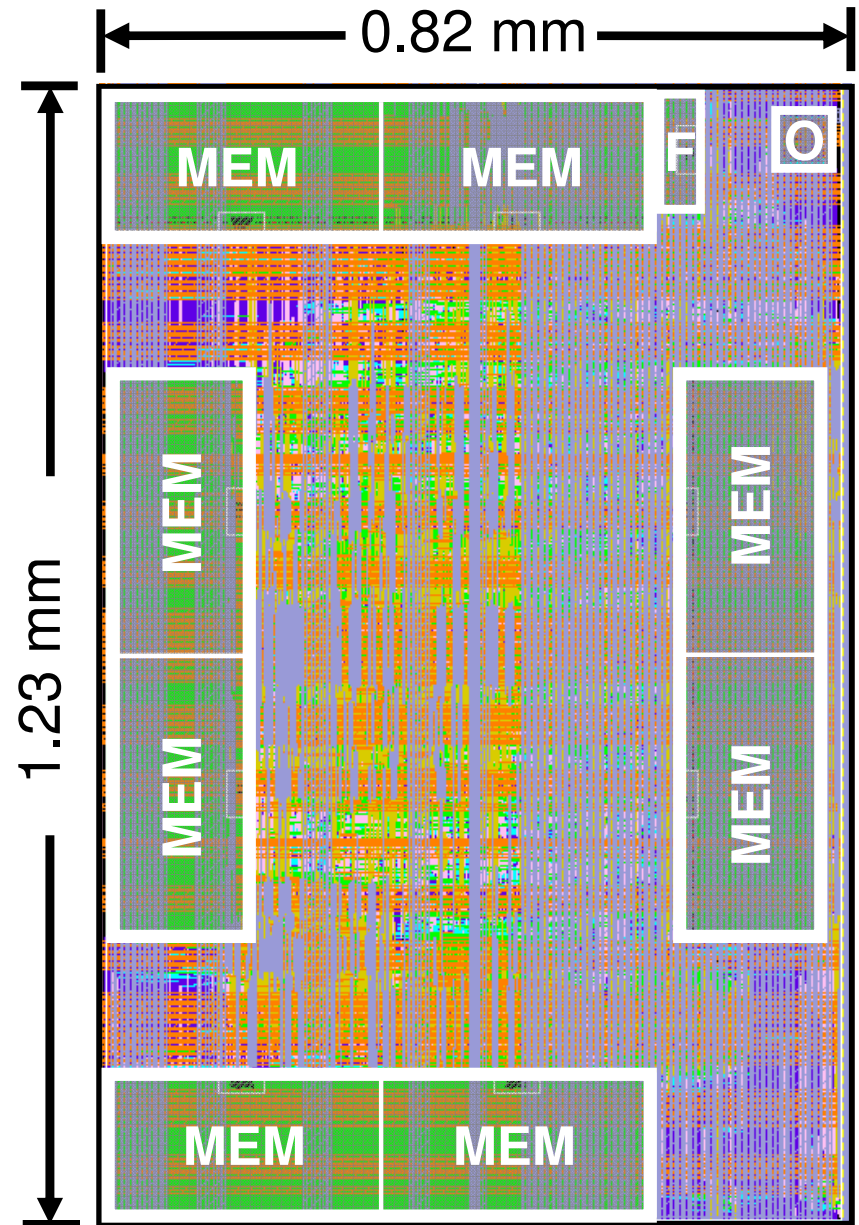


Homogenous Processors

- Over 60 basic instructions
 - Add, Sub, Logic, Multiply, MAC, Branch, ...
- New instructions and features
 - Min/Max, Byte-Sub/Add, Absolute value, Fixed-to-Float conversion assist
 - Jump/Return (function support)
 - Zero Overhead Looping (block repeat)
 - Conditional Execution (predicating)
 - Block Floating Point
- Floating point CORDIC square root requires 2.9x fewer cycles compared to first generation AsAP
- Preliminary results from one chip: 1.2 GHz, 59 mW, 1.3 V, 100% active MAC/ALU operations

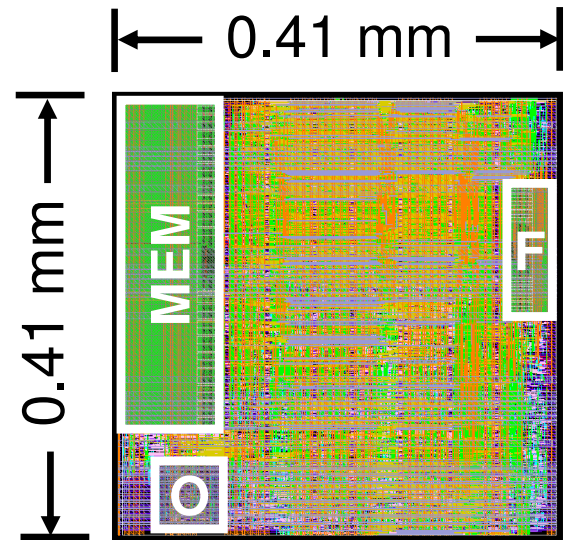
Fast Fourier Transform (FFT)

- Continuous flow architecture with a single radix-4,2 butterfly
- Runtime configurable from 16-pt to 4096-pt transforms, FFT and IFFT
- 760,000 1024-pt complex FFTs/sec @ 989 MHz, 1.3 V
- 1.01 mm²
- Preliminary measurements functional at 866 MHz, 34.97 mW @ 1.3 V



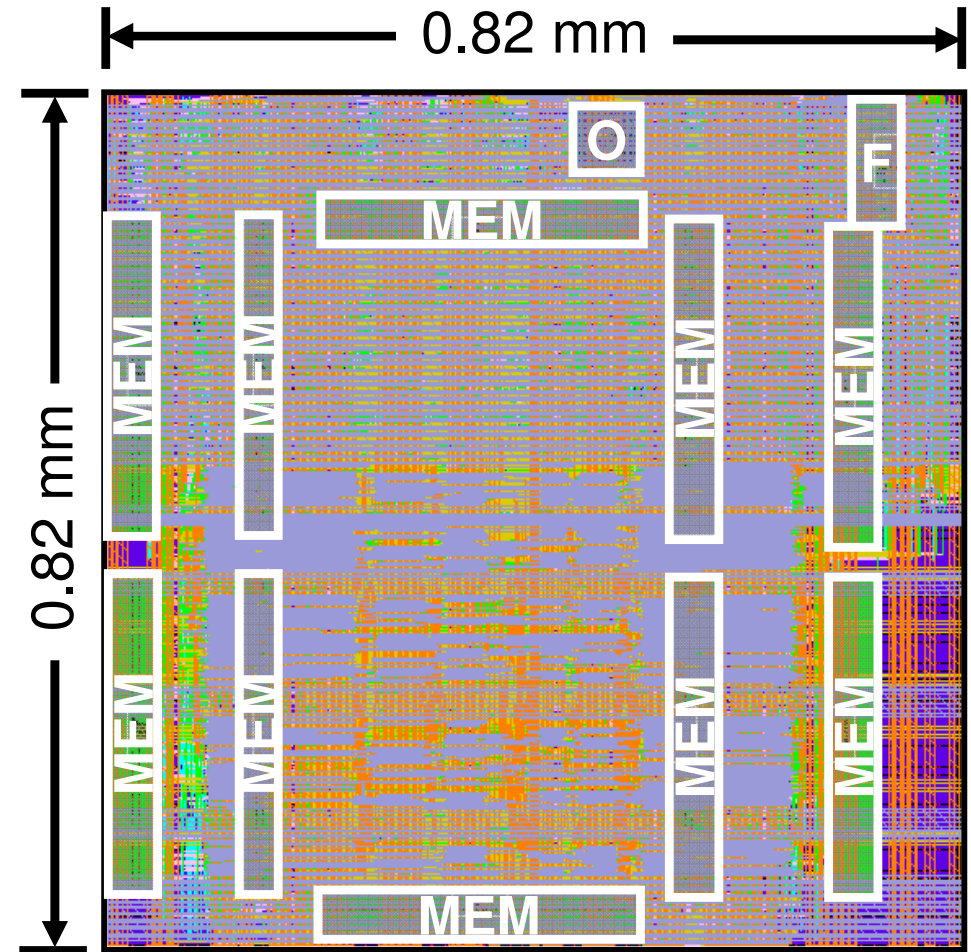
Viterbi Decoder

- 8 Add-Compare-Select (ACS) units
- Highly configurable
 - Up to 32 different rates, including 1/2 and 3/4
 - Decode codes up to constraint length 10
- 72 Mbps @ 789 MHz, 1.3 V for rate = 1/2
- 0.17 mm²
- Preliminary measurements functional at 894 MHz, 17.55 mW @ 1.3 V



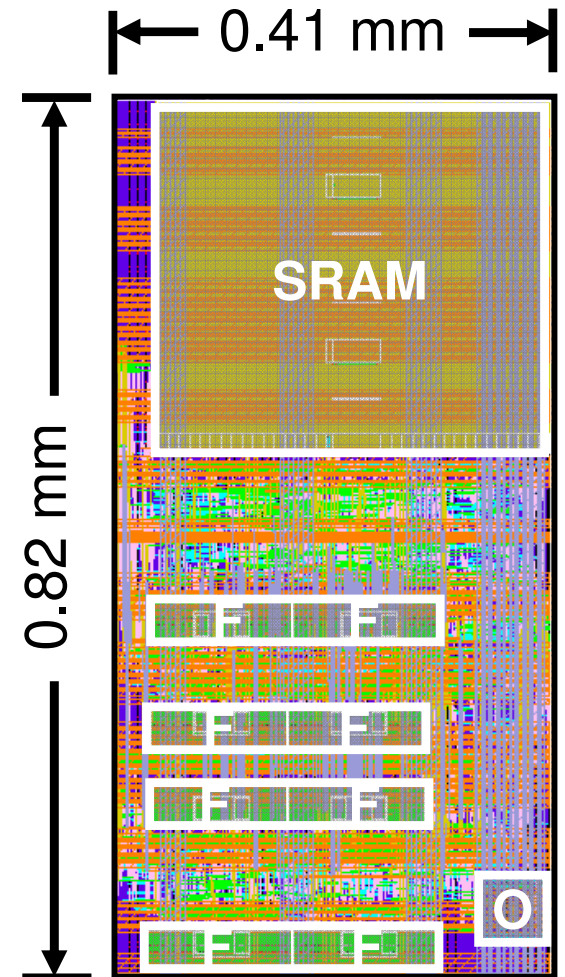
Motion Estimation for Video Encoding

- Supports a number of fixed and programmable search patterns
- Supports all H.264 specified block sizes within a 48x48 search range
- 14 billion SADs/sec @ 880 MHz, 1.3 V; supports 1080p HDTV @ 30fps
- 0.67 mm²
- Preliminary measurements functional at 938 MHz, 196.17 mW @ 1.3 V



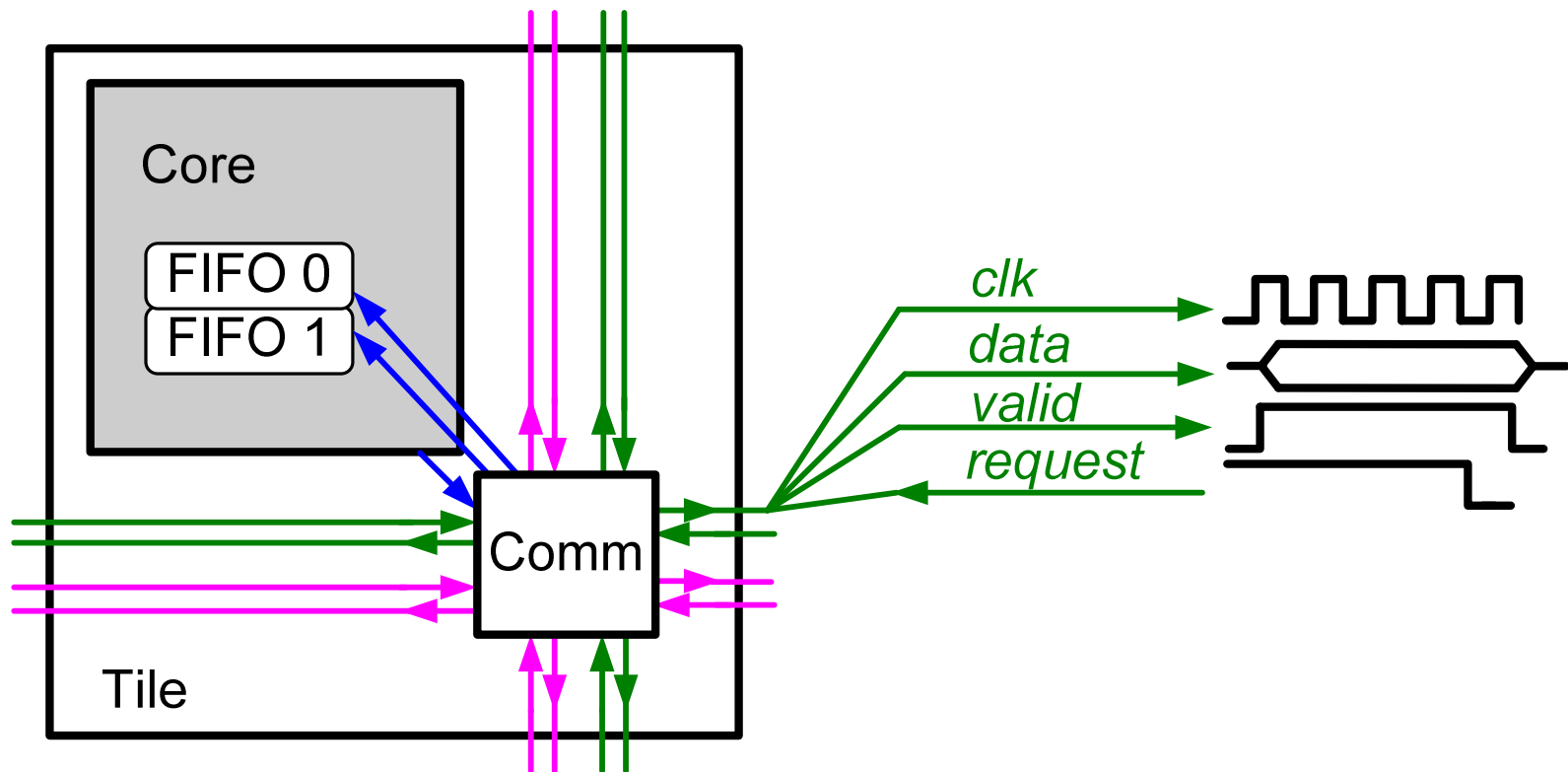
Shared Memories

- Ports for up to four processors (two connected in this chip) to directly connect to the block, which provides
 - Port priority
 - Port request arbitration
 - Programmable address generation supporting multiple addressing modes
- Uses a 16 KByte single-ported SRAM
- 1.28 GHz operation, 1.3 V
 - One read or write per cycle
 - 20.5 Gbps peak throughput
- 0.34 mm²
- Preliminary measurements functional at 1.3 GHz, 4.55 mW @ 1.3 V



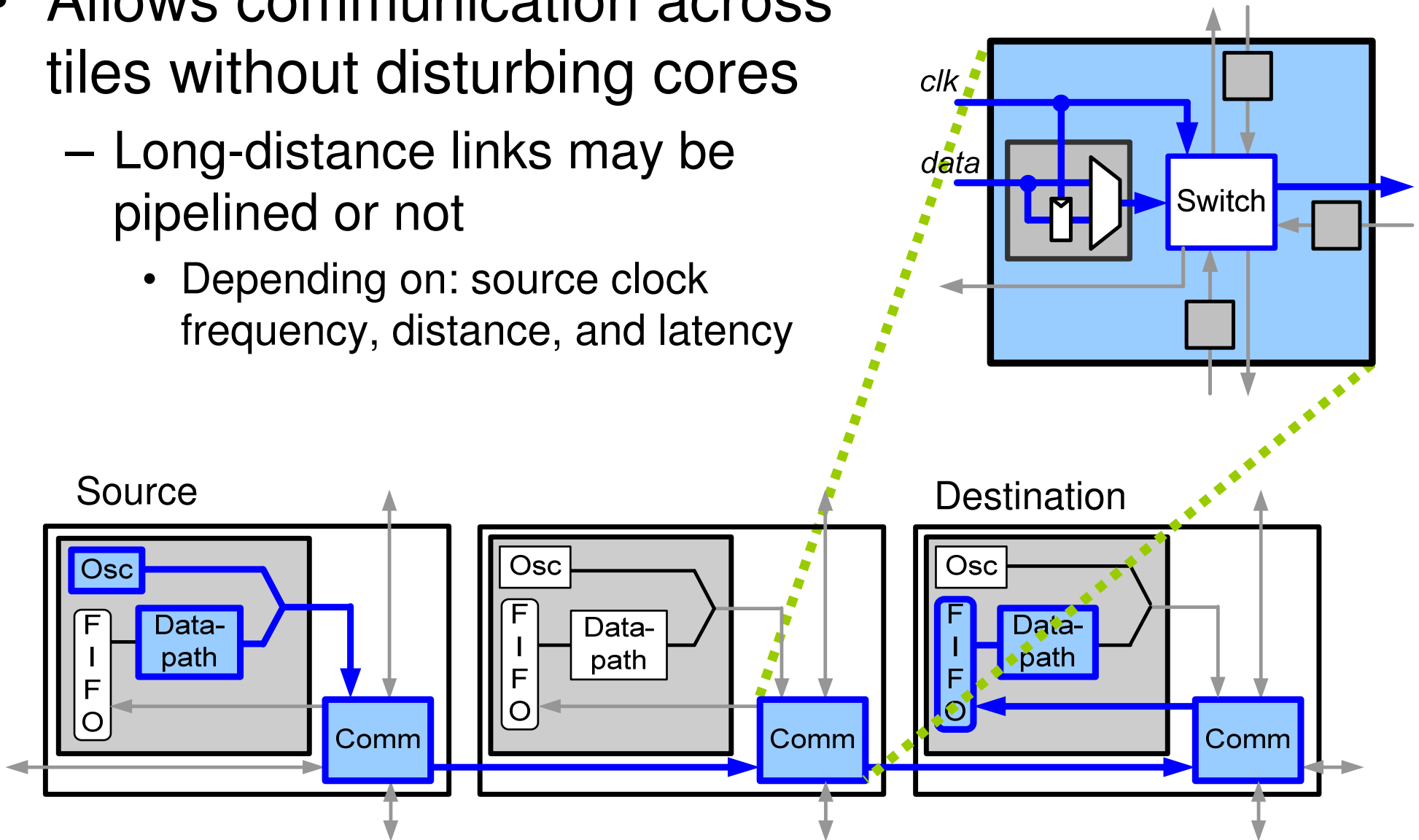
Inter-Processor Communication

- Circuit-switched source-synchronous communication
 - Each link has a *clk*, 16-bit *data* bus, *valid*, and *request*
 - Core can
 - Write to any combination of the 8 outputs under software control
 - Read from any 2 of the 8 inputs using statically configured FIFOs



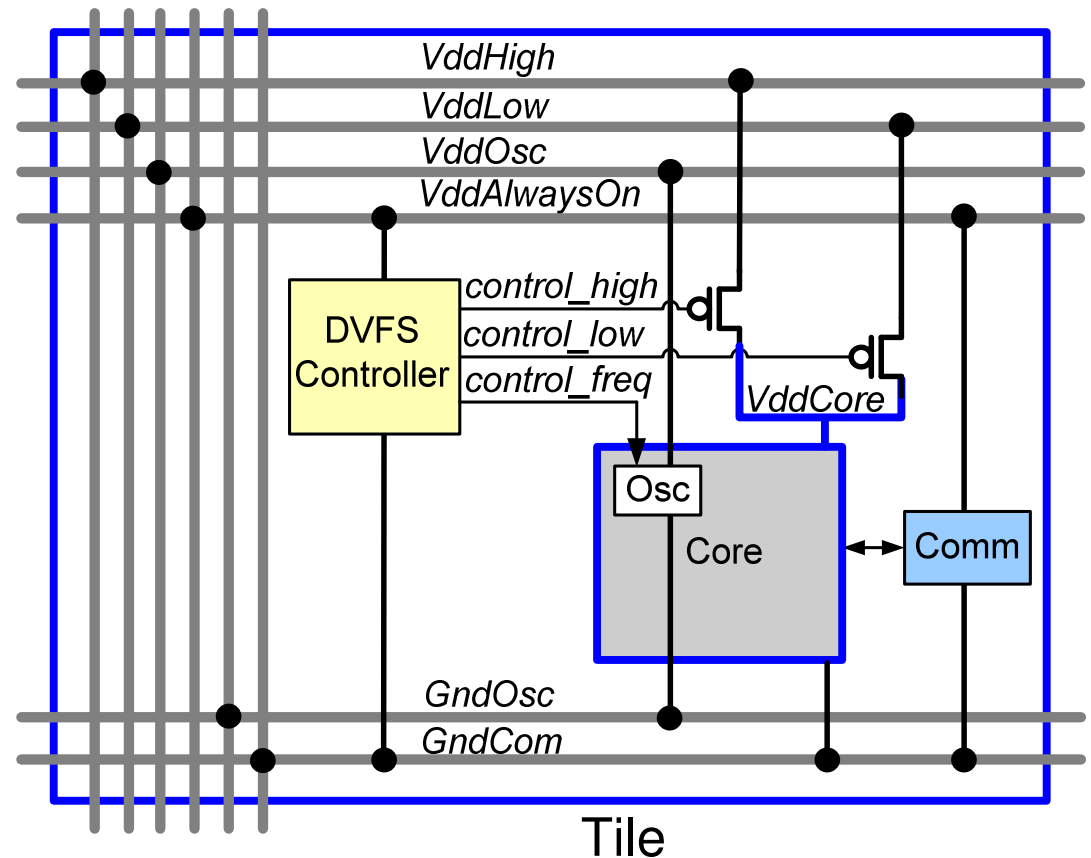
Long-Distance Communication

- Allows communication across tiles without disturbing cores
 - Long-distance links may be pipelined or not
 - Depending on: source clock frequency, distance, and latency



Per-Processor DVFS

- Each processor tile contains a core that operates at:
 - A fully-independent clock frequency
 - Any frequency below maximum
 - Halts, restarts, and changes arbitrarily
 - Dynamically-changeable supply voltage
 - *VddHigh* or *VddLow*
 - Disconnected for leakage reduction
- *VddAlwaysOn* powers DVFS and inter-processor communication

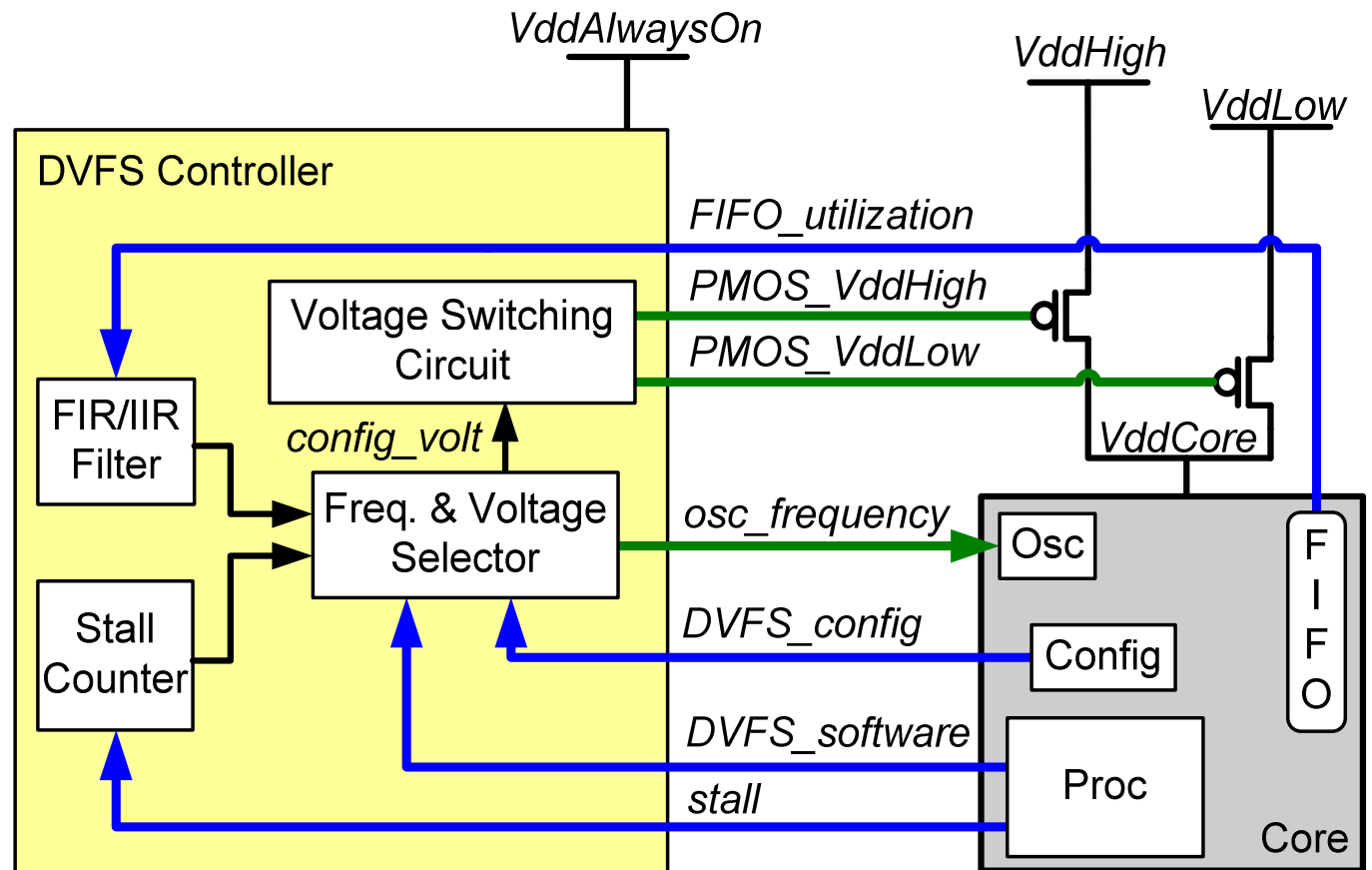


DVFS Controller

- Voltage and frequency is set by:
 - Static configuration
 - Software
 - Hardware

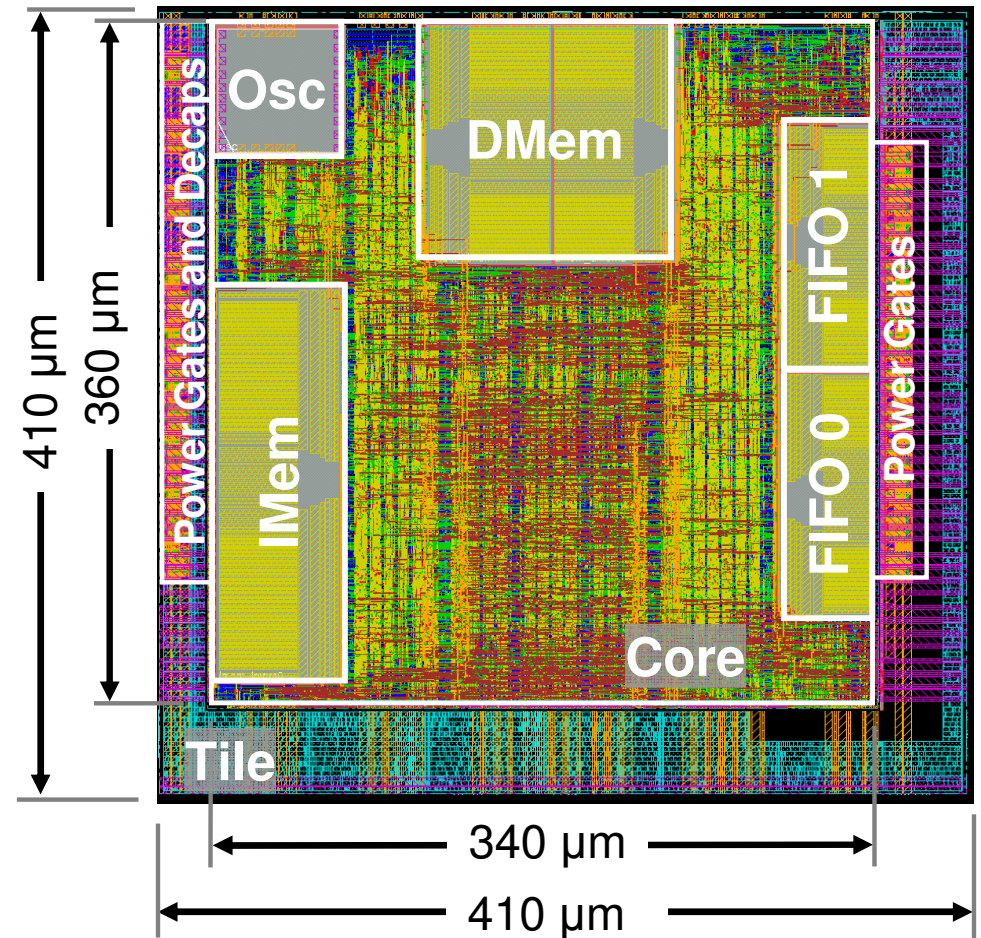
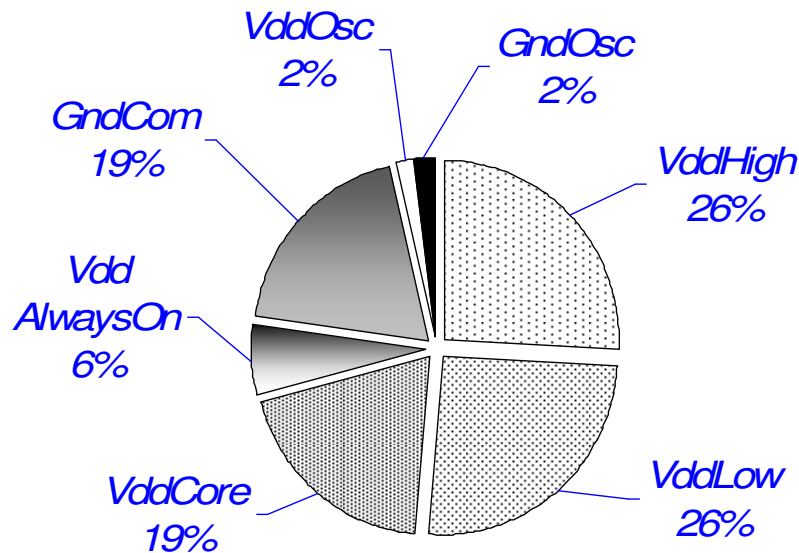
(controller)

- FIFO “fullness”
- Processor “stalling frequency”



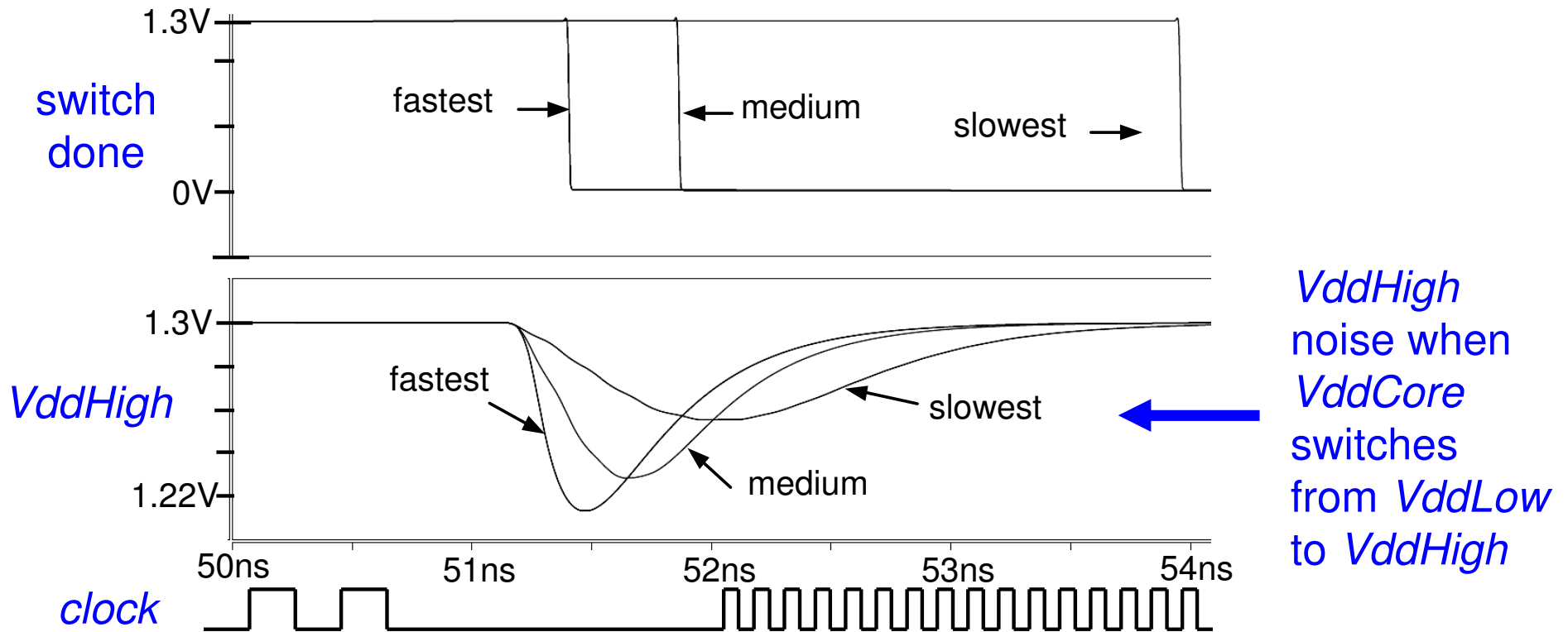
Tile Layout and Power Grids

- 48 power gates surround core
- Metal 6 and 7 are devoted to power distribution—
global and local
 - 5 *Vdds*: 79% utilization
 - 2 *Gnds*: 21% utilization
- *Vdd/Gnd* metal 6 and 7 usage:



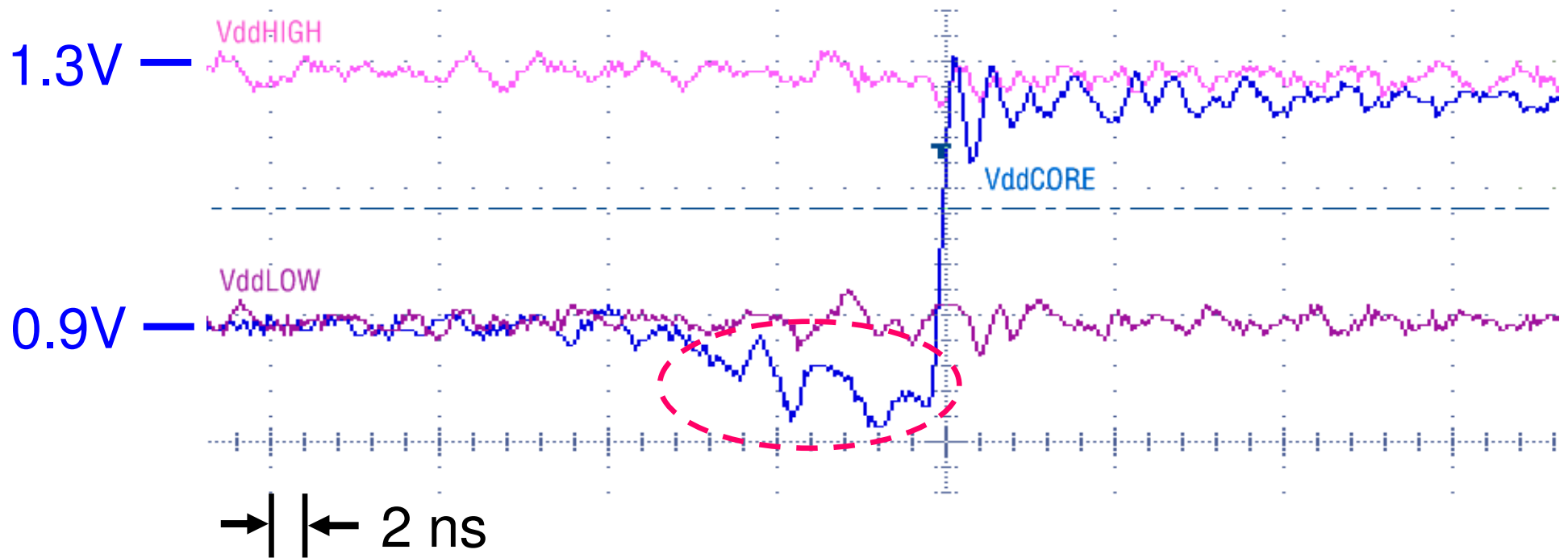
Supply Voltage Switching

- The switching speed and profile “shapes” supply currents while switching to tradeoff switching time versus power grid noise
- Processor cores normally halt during a switch



Supply Voltage Switching

- Slow switching results in negligible power grid noise
- Early **VddCore** disconnect from **VddLow** results in momentary core voltage drop (circled below)

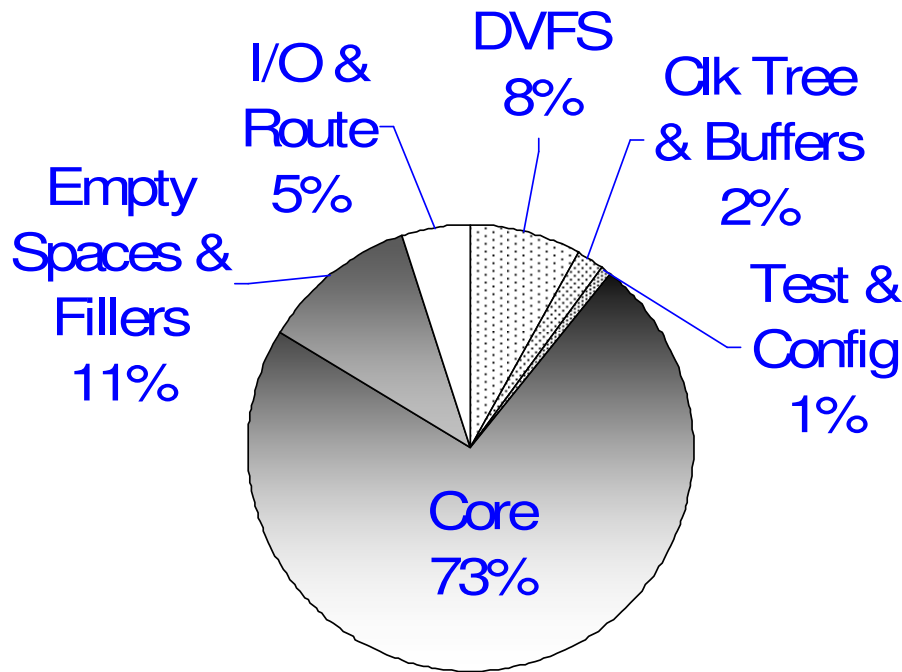


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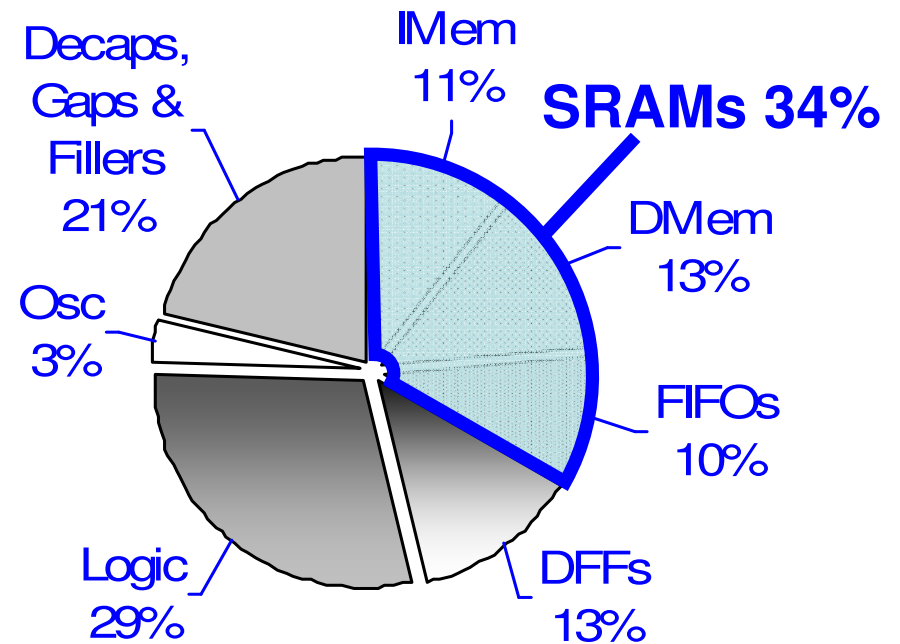
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Tile and Core Area Breakdowns

- Communication area approximately 7%
- DVFS area approximately 8%
- Routing complexity results in 27% for gaps and fillers



Tile Area

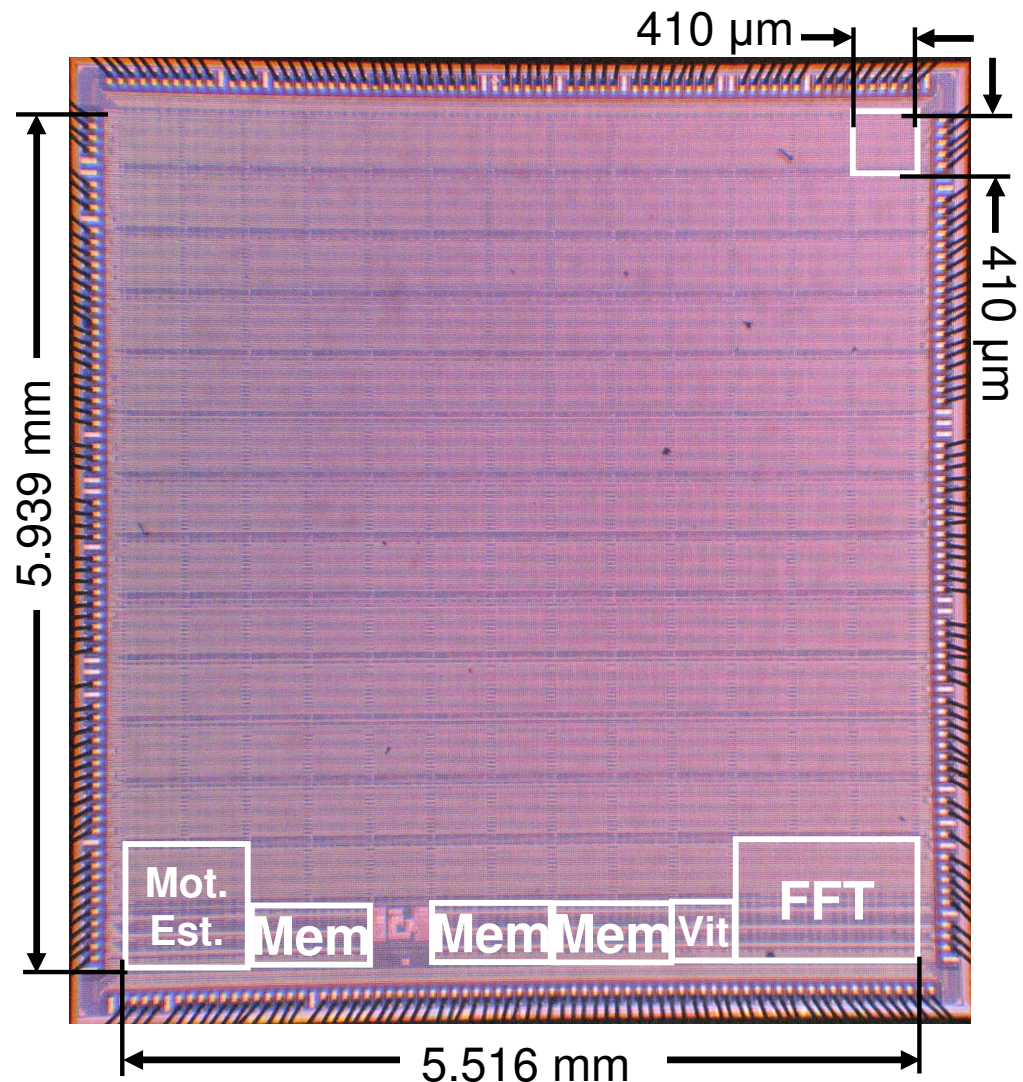


Core Area

Die Micrograph and Key Data

- 65 nm STMicroelectronics low-leakage CMOS

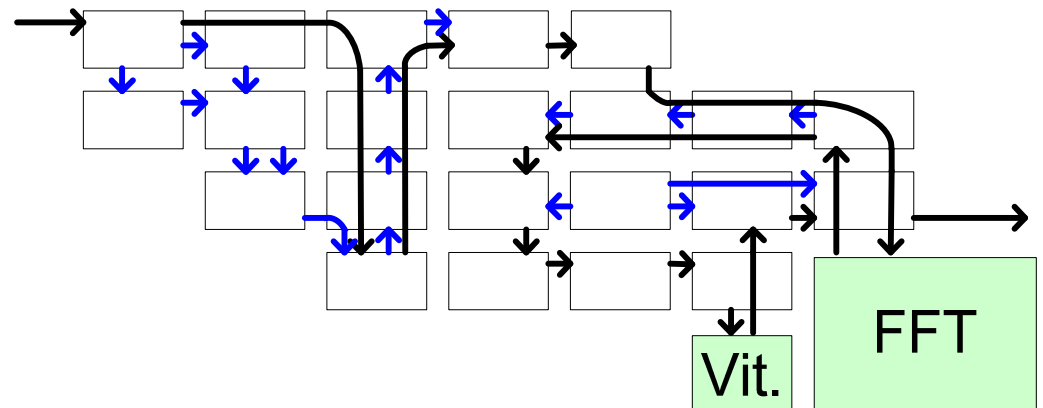
55 million transistors, 39.4 mm²



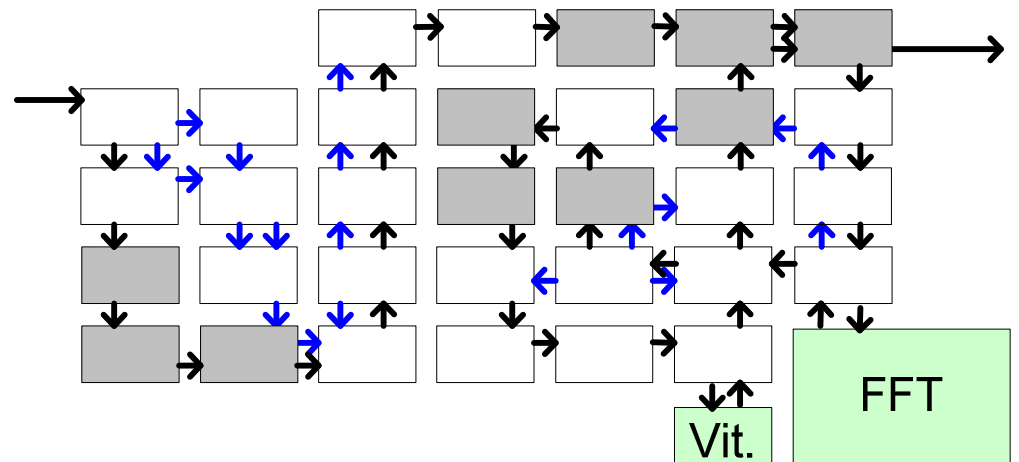
Single Tile	
Transistors	325,000
Area	0.17 mm ²
Max. frequency	1.19 GHz @ 1.3 V
Power (100% active)	59 mW @ 1.19 GHz, 1.3 V
	608 μW @ 66 MHz, 0.675 V
Power (JPEG)	6.3 mW @ 1.095 GHz, 1.3V

Complete 802.11a Baseband Receiver

- 22 processors
 - 32 processors using only nearest-neighbor connections (46% increase)
- 54 Mbps throughput
75 mW @ 610 MHz,
1.3 V
- 6x faster than TI C62x,
2x faster than SODA,
4x faster than LART
(all scaled to 65 nm technology,
1.3 V and 610 MHz)



802.11a with long-distance



802.11a without long-distance

Summary

- 65 nm low power ST Microelectronics process
- Maintains the basic GALS architecture of AsAP
- 164 homogenous processors
 - 1.2 GHz, 59 mW, 100% active @ 1.3 V
- Three 16 KB shared memories
- Three dedicated-purpose processors
- Long-distance circuit-switched communication increases mapping efficiency without overhead
- DVFS nets a 48% reduction in energy for JPEG with only 8% performance loss

Acknowledgements

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